

NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
3. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON 4 SIDES OF THE BOARD EDGE.
4. ASSY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD.
5. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP ON ANY BOARD.

6. INSTALL 4 STANDOFFS AT 4 CORNERS FROM THE BOTTOM SIDE.

